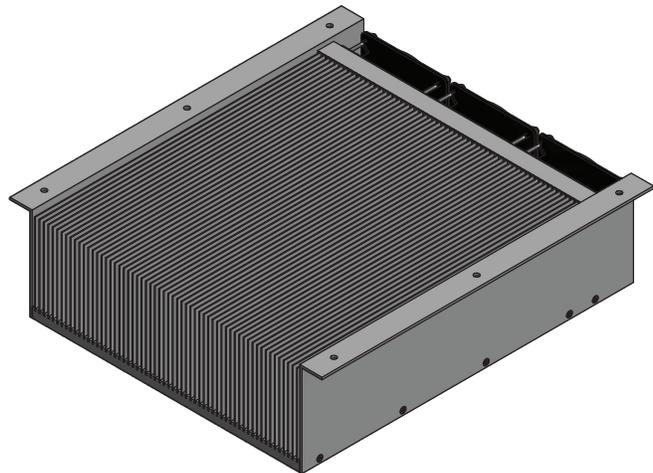
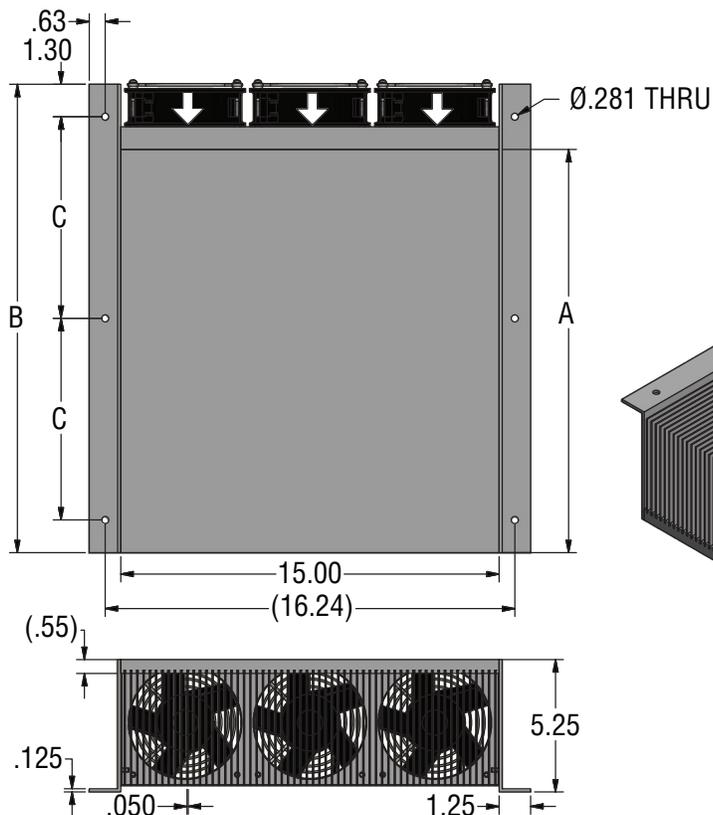


### FORCED CONVECTION – TRIPLE FAN MODELS

Triple Fan Forced Convection Heat Sinks have the highest watt per cubic inch performance over other Bonded Fin Heat Sink designs. Semiconductor modules can be mounted parallel to the Heat Sink fins to eliminate upstream heating effect. This allows for multiple IGBTs, Diodes and SCRs to operate at the same temperature and increase system reliability. Models available fully equipped with ball-bearing fans. **Custom designs are available upon request.**



### FORCED AIR CONVECTION - TRIPLE FAN MODELS

MODEL #	CH5120F	CH5121F	CH5122F
Dimension A	11.81"	14.00"	16.00"
Dimension B	14.59"	16.59"	18.59"
Dimension C	6.00"	7.00"	8.00"
Thermal Resistance	0.020°C/W	0.019°C/W	0.0175°C/W

Thermal specifications are based on 600 LFM airflow. Mounting pattern shown fits standard "muffin" fans.